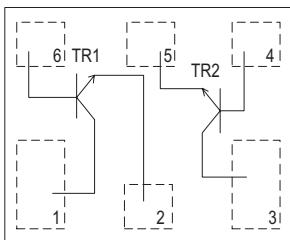
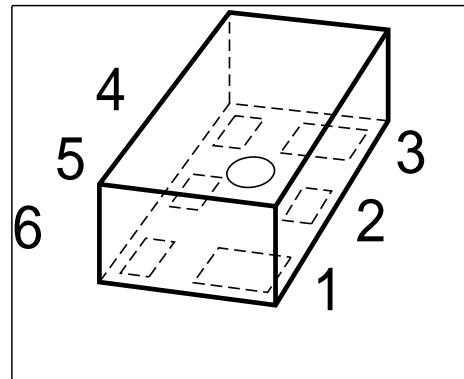


### NPN Silicon RF TWIN Transistor

#### Preliminary data

- Low voltage/ low current applications
- Ideal for VCO modules and low noise amplifiers
- Low noise figure: TR1: 1.1dB at 1.8 GHz  
TR2: 1.0 dB at 1.8 GHz
- World's smallest SMD 6-pin leadless package
- Built in 2 transistors (TR1: die as BFR460L3,  
TR2: die as BFR360L3)



**ESD:** Electrostatic discharge sensitive device, observe handling precaution!

Type	Marking	Pin Configuration						Package
BFS466L6	AC	1=C1	2=E1	3=C2	4=B2	5=E2	6=B1	TSLP-6-1

#### Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage TR1	$V_{CEO}$	4.5	V
TR2		6	
Collector-emitter voltage TR1	$V_{CES}$	15	
TR2		15	
Collector-base voltage TR1	$V_{CBO}$	15	
TR2		15	
Emitter-base voltage TR1	$V_{EBO}$	1.5	
TR2		2	
Collector current TR1	$I_C$	50	mA
TR2		35	

### Maximum Ratings

Parameter	Symbol	Value	Unit
Base current TR1	$I_B$	5	mA
TR2		4	
Total power dissipation <sup>1)</sup> TR1, $T_S \leq 104^\circ\text{C}$	$P_{\text{tot}}$	200	mW
TR2, $T_S \leq 102^\circ\text{C}$		210	
Junction temperature TR1	$T_j$	150	$^\circ\text{C}$
TR2		150	
Ambient temperature TR1	$T_A$	-65 ... 150	
TR2		-65 ... 150	
Storage temperature TR1	$T_{\text{stg}}$	-65 ... 150	
TR2		-65 ... 150	

### Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>2)</sup> TR1	$R_{\text{thJS}}$	$\leq 230$	K/W
TR2		$\leq 230$	

<sup>1</sup> $T_S$  is measured on the collector lead at the soldering point to the pcb

<sup>2</sup>For calculation of  $R_{\text{thJA}}$  please refer to Application Note Thermal Resistance

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>DC Characteristics</b>					
Collector-emitter breakdown voltage TR1, $I_C = 1 \text{ mA}$ , $I_B = 0$ TR2, $I_C = 1 \text{ mA}$ , $I_B = 0$	$V_{(\text{BR})\text{CEO}}$	4.5 6	5 9	- -	V
Collector-emitter cutoff current TR1, $V_{CE} = 15 \text{ V}$ , $V_{BE} = 0$ TR2, $V_{CE} = 15 \text{ V}$ , $V_{BE} = 0$	$I_{CES}$	- -	- -	10 10	$\mu\text{A}$
Collector-base cutoff current TR1, $V_{CB} = 5 \text{ V}$ , $I_E = 0$ TR2, $V_{CB} = 5 \text{ V}$ , $I_E = 0$	$I_{CBO}$	- -	- -	100 100	nA
Emitter-base cutoff current TR1, $V_{EB} = 0.5 \text{ V}$ , $I_C = 0$ TR2, $V_{EB} = 1 \text{ V}$ , $I_C = 0$	$I_{EBO}$	- -	- -	1 1	$\mu\text{A}$
DC current gain TR1, $I_C = 20 \text{ mA}$ , $V_{CE} = 3 \text{ V}$ TR2, $I_C = 20 \text{ mA}$ , $V_{CE} = 3 \text{ V}$	$h_{FE}$	- 90	130 130	- 160	-

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>AC Characteristics</b> (verified by random sampling)					
Transition frequency TR1, $I_C = 30 \text{ mA}$ , $V_{CE} = 3 \text{ V}$ , $f = 1 \text{ GHz}$ TR2, $I_C = 15 \text{ mA}$ , $V_{CE} = 3 \text{ V}$ , $f = 1 \text{ GHz}$	$f_T$	16 11	22 14	- -	GHz
Collector-base capacitance TR1, $V_{CB} = 3 \text{ V}$ , $f = 1 \text{ MHz}$ , emitter grounded TR2, $V_{CB} = 5 \text{ V}$ , $f = 1 \text{ MHz}$ , emitter grounded	$C_{cb}$	- -	0.33 0.3	0.5 0.45	pF
Collector emitter capacitance TR1, $V_{CE} = 3 \text{ V}$ , $f = 1 \text{ MHz}$ , base grounded TR1, $V_{CE} = 3 \text{ V}$ , $f = 1 \text{ MHz}$ , base grounded	$C_{ce}$	- -	0.17 0.17	- -	
Emitter-base capacitance TR1, $V_{EB} = 0.5 \text{ V}$ , $f = 1 \text{ MHz}$ , collector grounded TR2, $V_{EB} = 0.5 \text{ V}$ , $f = 1 \text{ MHz}$ , collector grounded	$C_{eb}$	- -	0.57 0.48	- -	

**Electrical Characteristics at TA = 25°C, unless otherwise specified**

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>AC Characteristics (verified by random sampling)</b>					
Noise figure	$F$				dB
TR1, $I_C=5\text{mA}$ , $V_{CE} = 3 \text{ V}$ , $f = 1.8 \text{ GHz}$ , $Z_S = Z_{Sopt}$		-	1.1	-	
TR1, $I_C=5\text{mA}$ , $V_{CE} = 3 \text{ V}$ , $f = 3 \text{ GHz}$ , $Z_S = Z_{Sopt}$		-	1.4	-	
TR2, $I_C=3\text{mA}$ , $V_{CE} = 3 \text{ V}$ , $f = 1.8 \text{ GHz}$ , $Z_S = Z_{Sopt}$		-	1	-	
TR2, $I_C=3\text{mA}$ , $V_{CE} = 3 \text{ V}$ , $f = 3 \text{ GHz}$ , $Z_S = Z_{Sopt}$		-	1.4	-	
Power gain, maximum available <sup>1)</sup>	$G_{ma}$				
TR1, $I_C = 20 \text{ mA}$ , $V_{CE} = 3 \text{ V}$ , $Z_S = Z_{Sopt}$ , $Z_L = Z_{Lopt}$ , $f = 1.8 \text{ GHz}$		-	14.5	-	
TR1, $I_C = 20 \text{ mA}$ , $V_{CE} = 3 \text{ V}$ , $Z_S = Z_{Sopt}$ , $Z_L = Z_{Lopt}$ , $f = 3 \text{ GHz}$		-	10	-	
TR2, $I_C = 15 \text{ mA}$ , $V_{CE} = 3 \text{ V}$ , $Z_S = Z_{Sopt}$ , $Z_L = Z_{Lopt}$ , $f = 1.8 \text{ GHz}$		-	14.5	-	
TR2, $I_C = 15 \text{ mA}$ , $V_{CE} = 3 \text{ V}$ , $Z_S = Z_{Sopt}$ , $Z_L = Z_{Lopt}$ , $f = 3 \text{ GHz}$		-	10	-	
Transducer gain	$ S_{21e} ^2$				
TR1, $I_C = 20 \text{ mA}$ , $V_{CE} = 3 \text{ V}$ , $Z_S = Z_L = 50\Omega$ , $f = 1.8\text{GHz}$		-	12.5	-	
TR1, $I_C = 20 \text{ mA}$ , $V_{CE} = 3 \text{ V}$ , $Z_S = Z_L = 50\Omega$ , $f = 3\text{GHz}$		-	9	-	
TR2, $I_C = 15 \text{ mA}$ , $V_{CE} = 3 \text{ V}$ , $Z_S = Z_L = 50\Omega$ , $f = 1.8\text{GHz}$		-	12.5	-	
TR2, $I_C = 15 \text{ mA}$ , $V_{CE} = 3 \text{ V}$ , $Z_S = Z_L = 50\Omega$ , $f = 3\text{GHz}$		-	8.5	-	
Third order intercept point at output <sup>2)</sup>	$IP_3$				dBm
TR1, $V_{CE}=3\text{V}$ , $I_C=20\text{mA}$ , $Z_S=Z_L=50\Omega$ , $f=1.8\text{GHz}$		-	28	-	
TR2, $V_{CE}=3\text{V}$ , $I_C=15\text{mA}$ , $Z_S=Z_L=50\Omega$ , $f=1.8\text{GHz}$		-	24.5	-	
1dB Compression point, at output	$P_{-1\text{dB}}$				
TR1, $I_C=20\text{mA}$ , $V_{CE}=3\text{V}$ , $Z_S=Z_L=50\Omega$ , $f=1.8\text{GHz}$		-	12	-	
TR1, $I_C=15\text{mA}$ , $V_{CE}=3\text{V}$ , $Z_S=Z_L=50\Omega$ , $f=1.8\text{GHz}$		-	9	-	

<sup>1)</sup> $G_{ma} = |S_{21e}| / S_{12e} \cdot (k - (k^2 - 1)^{1/2})$ 
<sup>2)</sup>IP3 value depends on termination of all intermodulation frequency components.

Termination used for this measurement is  $50\Omega$  from 0.1 MHz to 6 GHz

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